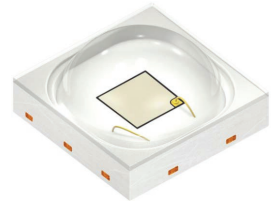


GD QSSPA1.14

OSCONIQ® P 3030

The OSCONIQ P 3030 Colors family LED comes with well known superior robustness, high reliability, long lifetime, low thermal resistance. Compact and proven 3mm x 3mm package and established footprint. Perfectly addressing applications that demand for high efficiency and long lifetime.



Applications

- Architecture
- Horticulture Lighting
- Architecture / Garden Lighting (LED & Laser)

Features:

- Package: SMD epoxy package
- Typ. Radiation: 120°
- Lumen maintenance: Test results according to IESNA LM-80 available
- ESD: 8 kV acc. to ANSI/ESDA/JEDEC JS-001 (HBM, Class 3B)
- Radiant Flux: typ. 700 mW
- Radiant Efficiency: typ. 70 %
- Photosynthetic Photon Flux: typ. 2.64 $\mu\text{mol/s}$

Ordering Information

| Type | Radiant Intensity ¹⁾ $I_F = 350 \text{ mA}$ I_e | Ordering Code |
|------------------------|--|---------------|
| GD QSSPA1.14-UOVK-W4-1 | 660.0 ... 825.0 mW/sr | Q65112A7997 |

Maximum Ratings

| Parameter | Symbol | | Values |
|--|-----------|--------------|-------------------|
| Operating Temperature | T_{op} | min. max. | -40 °C 125 °C |
| Storage Temperature | T_{stg} | min. max. | -40 °C 125 °C |
| Junction Temperature | T_j | max. | 135 °C |
| Forward current | I_F | min. max. | 100 mA 1300 mA |
| Surge Current $t \leq 10 \mu s$; $D = 0.005$; $T_j = 25 \text{ °C}$ | I_{FS} | max. | 2000 mA |
| ESD withstand voltage acc. to ANSI/ESDA/JEDEC JS-001 (HBM, Class 3B) | V_{ESD} | | 8 kV |

Characteristics

$I_F = 350 \text{ mA}$; $T_J = 25 \text{ °C}$

| Parameter | Symbol | | Values |
|--|-------------------------|------|-----------|
| Peak Wavelength | λ_{peak} | typ. | 451 nm |
| Dominant Wavelength ²⁾ $I_F = 350 \text{ mA}$ | λ_{dom} | min. | 439 nm |
| | | typ. | 449 nm |
| | | max. | 457 nm |
| Spectral Bandwidth at 50% $I_{\text{rel,max}}$ | $\Delta\lambda$ | typ. | 20 nm |
| Viewing angle at 50% I_V | 2φ | typ. | 130 ° |
| Forward Voltage ³⁾ $I_F = 350 \text{ mA}$ | V_F | min. | 2.75 V |
| | | typ. | 2.85 V |
| | | max. | 3.25 V |
| Electrical thermal resistance junction/solderpoint with efficiency $\eta_e = 68 \%$ | $R_{\text{thJS elec.}}$ | typ. | 2.9 K / W |

Brightness Groups

| Group | Radiant Intensity 1) | Radiant Intensity 1) | PPF * | PPF * | PPF/W * | BPF ** | BPF ** | BPF/W ** |
|-------|-------------------------|-------------------------|------------------------|------------------------|------------------------|------------------------|------------------------|------------------------|
| | min. I_e | max. I_e | min. Φ_p | max. Φ_p | typ. | min. $\Phi_{p,b}$ | max. $\Phi_{p,b}$ | typ. |
| UO | 660.0 mW/sr | 710.0 mW/sr | 2.49 $\mu\text{mol/s}$ | 2.68 $\mu\text{mol/s}$ | 2.59 $\mu\text{mol/J}$ | 2.49 $\mu\text{mol/s}$ | 2.69 $\mu\text{mol/s}$ | 2.60 $\mu\text{mol/J}$ |
| VJ | 710.0 mW/sr | 765.0 mW/sr | 2.68 $\mu\text{mol/s}$ | 2.89 $\mu\text{mol/s}$ | 2.79 $\mu\text{mol/J}$ | 2.69 $\mu\text{mol/s}$ | 2.89 $\mu\text{mol/s}$ | 2.80 $\mu\text{mol/J}$ |
| VK | 765.0 mW/sr | 825.0 mW/sr | 2.89 $\mu\text{mol/s}$ | 3.11 $\mu\text{mol/s}$ | 3.01 $\mu\text{mol/J}$ | 2.89 $\mu\text{mol/s}$ | 3.12 $\mu\text{mol/s}$ | 3.01 $\mu\text{mol/J}$ |

Note: [1] Includes wavelengths between 400 and 700 nm

Note: [2] Includes wavelengths between 280 and 800 nm

Forward Voltage Groups

| Group | Forward Voltage ³⁾ $I_F = 350 \text{ mA}$ min. V_F | Forward Voltage ³⁾ $I_F = 350 \text{ mA}$ max. V_F |
|-------|--|--|
| 3 | 2.75 V | 3.00 V |
| 4 | 3.00 V | 3.25 V |

Wavelength Groups

| Group | Dominant Wavelength ²⁾ $I_F = 350 \text{ mA}$ min. λ_{dom} | Dominant Wavelength ²⁾ $I_F = 350 \text{ mA}$ max. λ_{dom} |
|-------|---|---|
| W | 439 nm | 444 nm |
| 2 | 444 nm | 449 nm |
| 3 | 449 nm | 453 nm |
| 4 | 453 nm | 457 nm |

Group Name on Label

Example: UO-2-3

Brightness

Wavelength

Forward Voltage

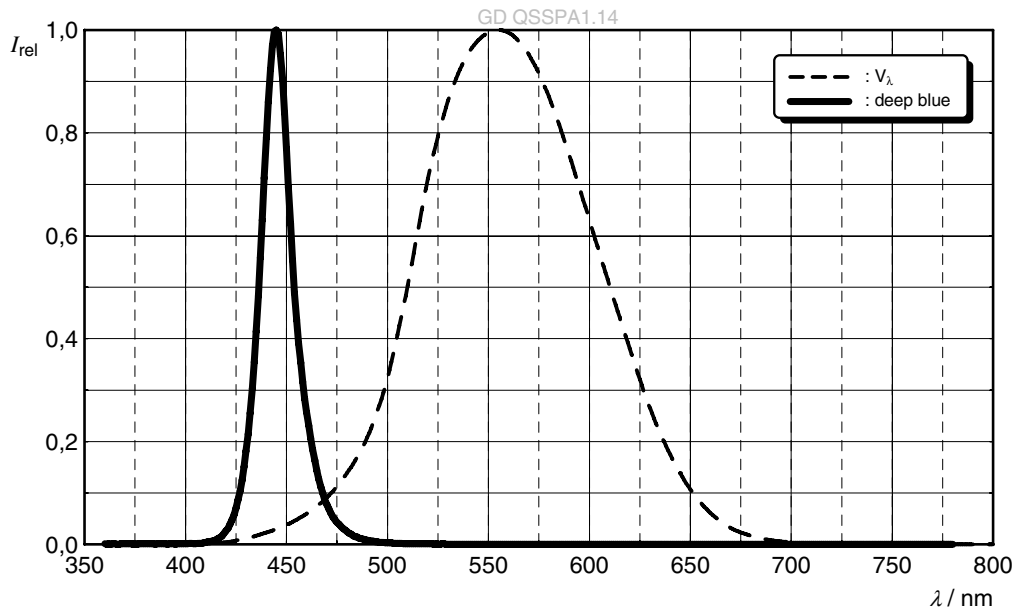
UO

2

3

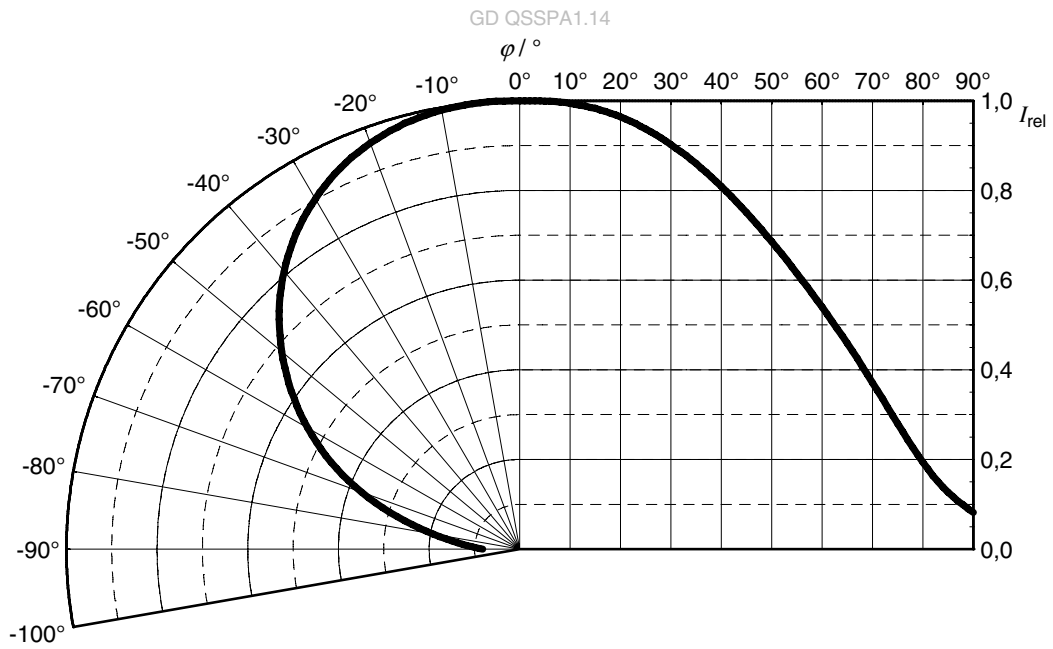
Relative Spectral Emission ⁴⁾

$I_{rel} = f(\lambda); I_F = 350 \text{ mA}; T_J = 25 \text{ }^\circ\text{C}$



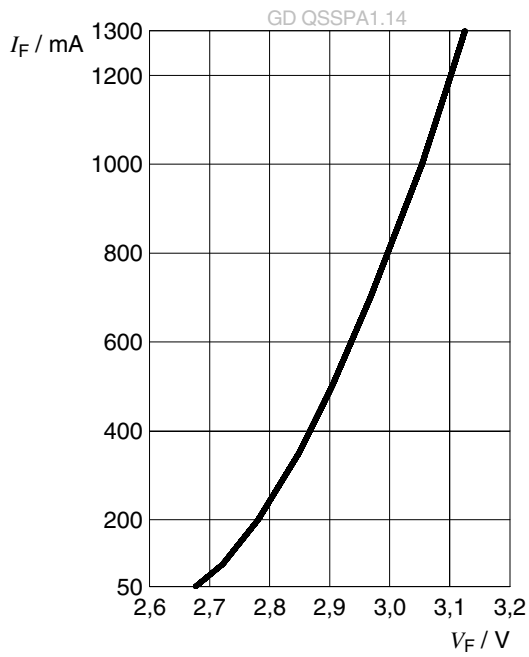
Radiation Characteristics ⁴⁾

$I_{rel} = f(\phi); T_J = 25 \text{ }^\circ\text{C}$



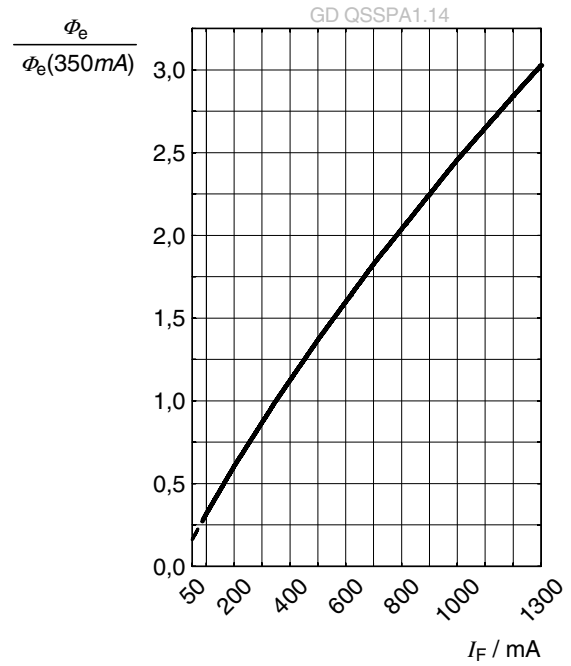
Forward current ⁴⁾

$I_F = f(V_F); T_J = 25\text{ °C}$



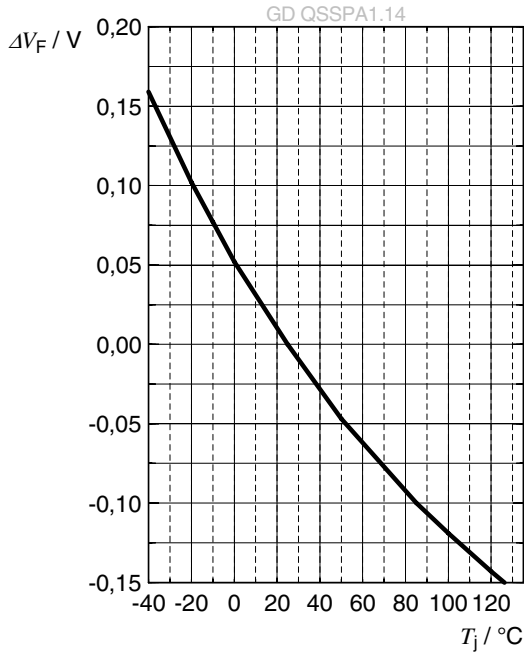
Relative Radiant Power ^{4), 5)}

$I_E/I_E(350\text{ mA}) = f(I_F); T_J = 25\text{ °C}$



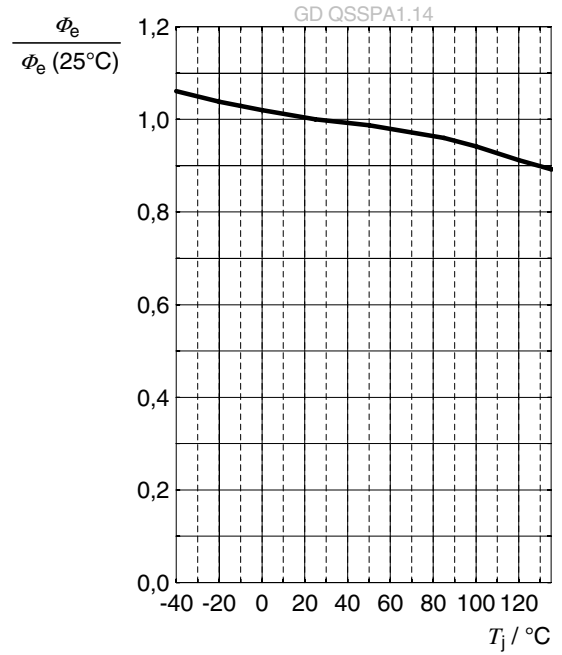
Forward Voltage ⁴⁾

$$\Delta V_F = V_F - V_F(25\text{ }^\circ\text{C}) = f(T_j); I_F = 350\text{ mA}$$



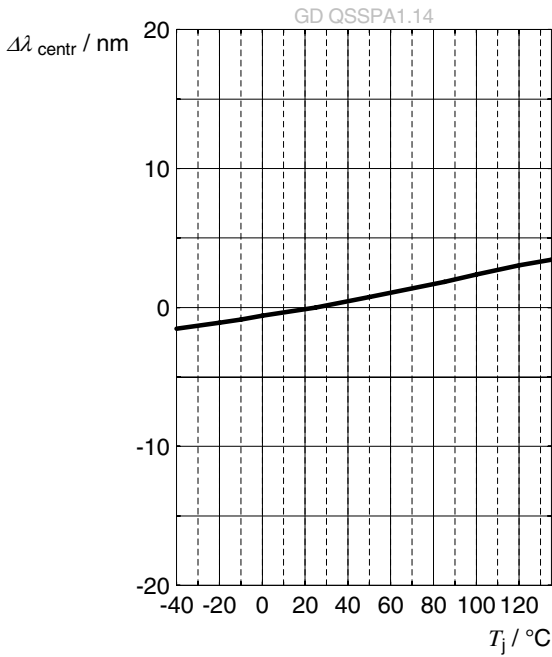
Relative Radiant Power ⁴⁾

$$I_E / I_E(25\text{ }^\circ\text{C}) = f(T_j); I_F = 350\text{ mA}$$



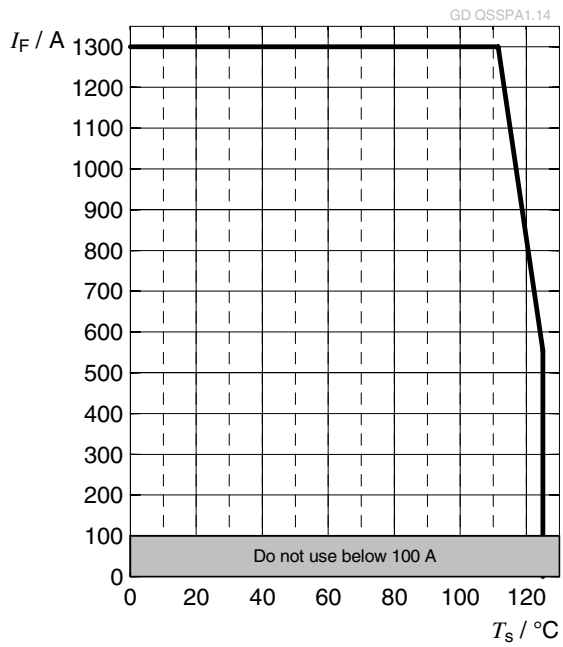
Centroid Wavelength ⁴⁾

$$\Delta \lambda_{\text{centr}} = \lambda_{\text{centr}} - \lambda_{\text{centr}}(25\text{ }^\circ\text{C}) = f(T_j); I_F = 350\text{ mA}$$

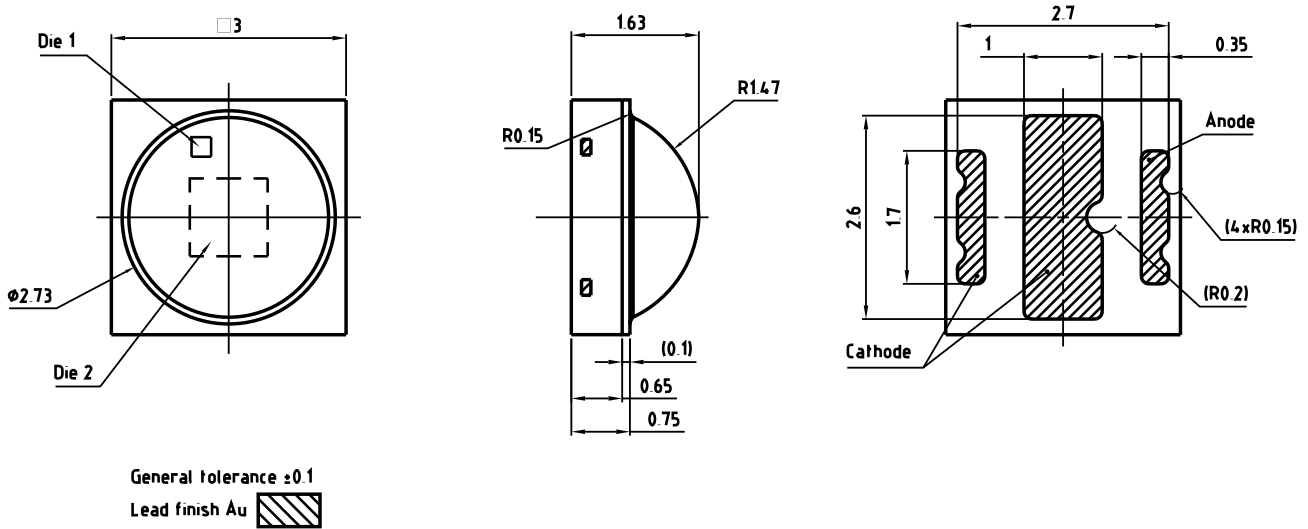


Max. Permissible Forward Current

$$I_F = f(T)$$



Dimensional Drawing ⁶⁾



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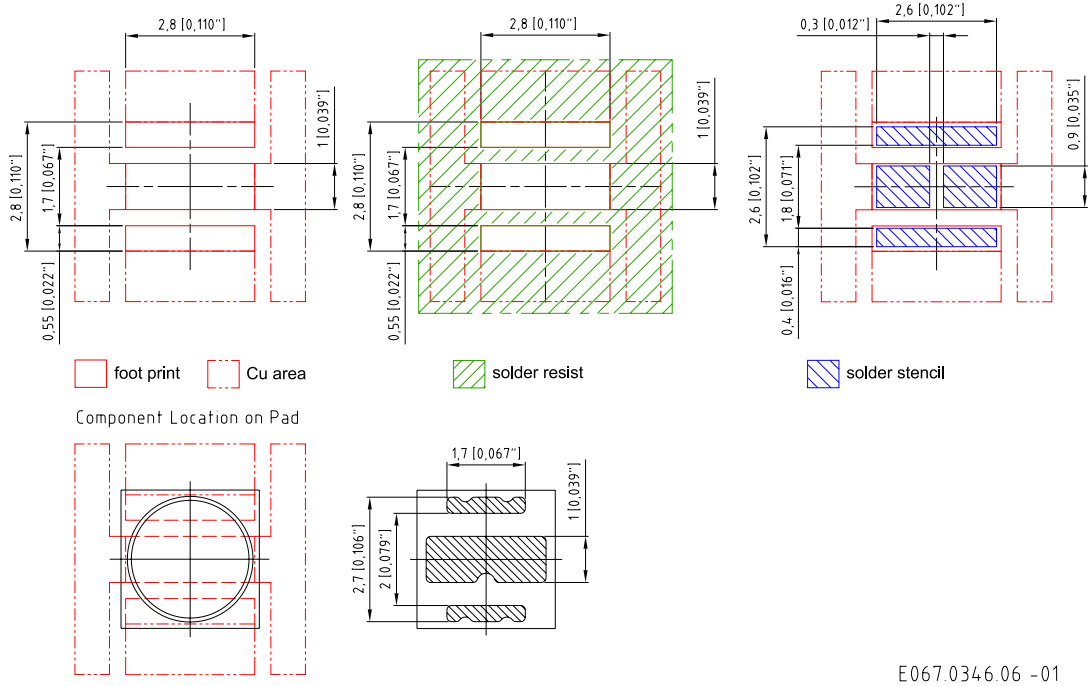
Further Information:

Approximate Weight: 24.0 mg

Package marking: Anode

ESD advice: The device is protected by ESD device which is connected in parallel to the Chip.

Recommended Solder Pad 6)



E067.0346.06 -01

For superior solder joint connectivity results we recommend soldering under standard nitrogen atmosphere. Package not suitable for ultra sonic cleaning.

Reflow Soldering Profile

Product complies to MSL Level 2 acc. to JEDEC J-STD-020E

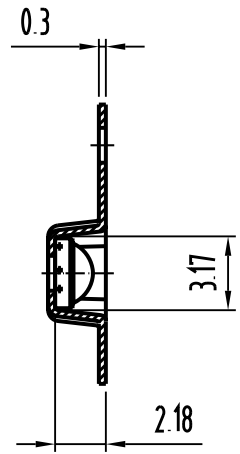
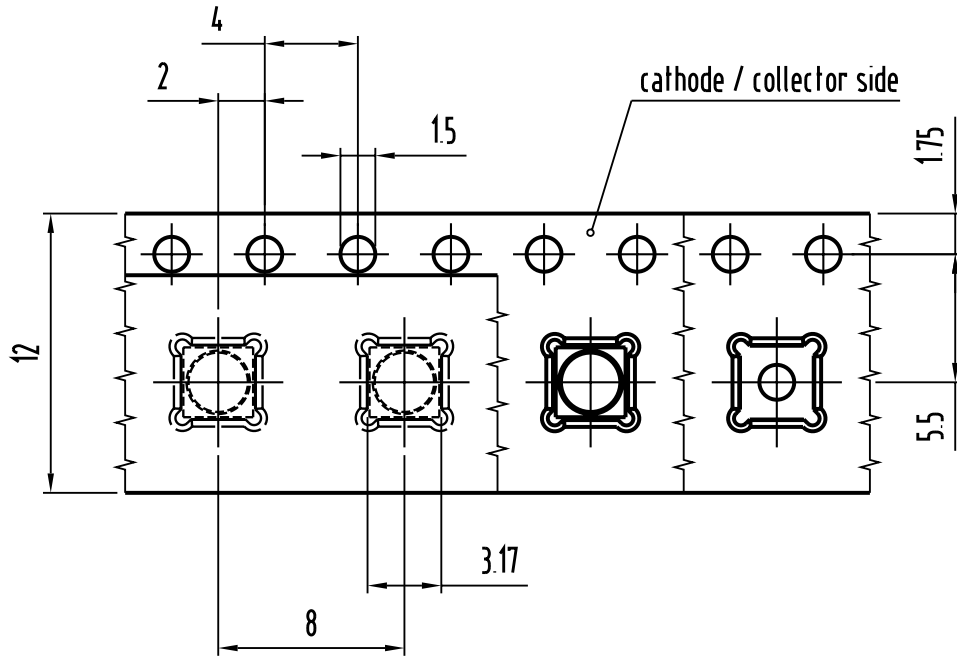


| Profile Feature | Symbol | Pb-Free (SnAgCu) Assembly | | | Unit |
|---|--------|---------------------------|----------------|---------|------|
| | | Minimum | Recommendation | Maximum | |
| Ramp-up rate to preheat ^{*)} 25 °C to 150 °C | | | 2 | 3 | K/s |
| Time t_s T_{Smin} to T_{Smax} | t_s | 60 | 100 | 120 | s |
| Ramp-up rate to peak ^{*)} T_{Smax} to T_p | | | 2 | 3 | K/s |
| Liquidus temperature | T_L | | 217 | | °C |
| Time above liquidus temperature | t_L | | 80 | 100 | s |
| Peak temperature | T_p | | 245 | 260 | °C |
| Time within 5 °C of the specified peak temperature $T_p - 5$ K | t_p | 10 | 20 | 30 | s |
| Ramp-down rate* T_p to 100 °C | | | 3 | 6 | K/s |
| Time 25 °C to T_p | | | | 480 | s |

All temperatures refer to the center of the package, measured on the top of the component

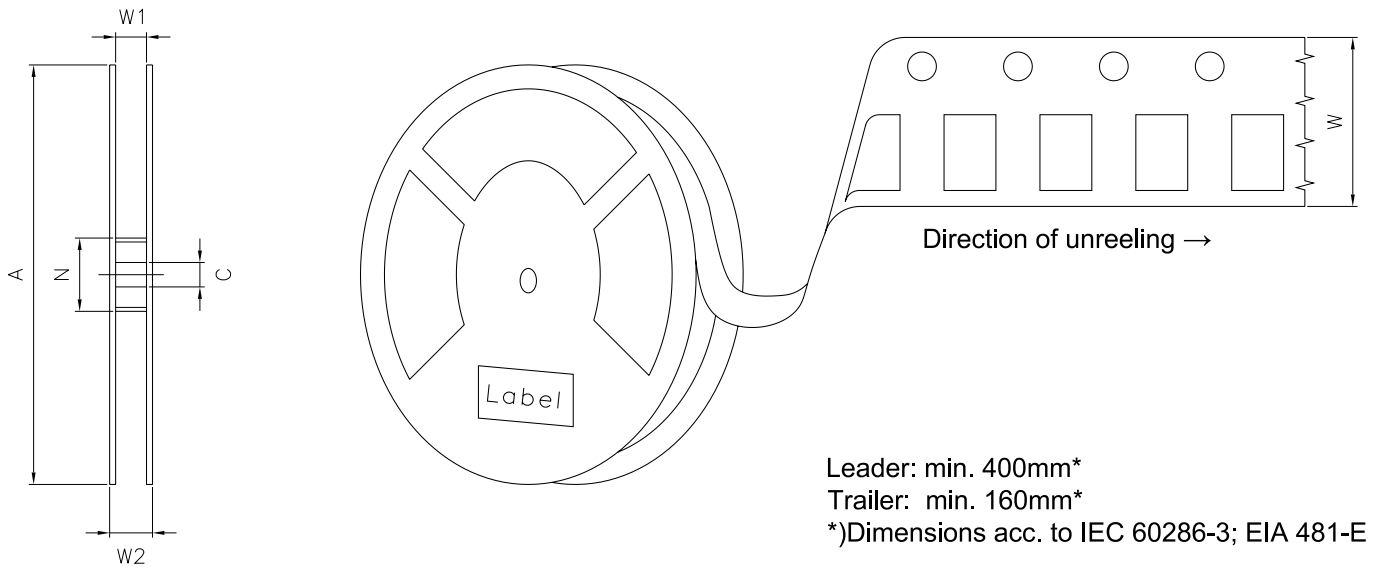
* slope calculation DT/Dt : Dt max. 5 s; fulfillment for the whole T-range

Taping ⁶⁾



C67062-A0282-B7 05

Tape and Reel ⁷⁾



Reel Dimensions

| A | W | N _{min} | W ₁ | W _{2max} | Pieces per PU |
|--------|---------------------|------------------|----------------|-------------------|---------------|
| 180 mm | 12 + 0.3 / - 0.1 mm | 60 mm | 12.4 + 2 mm | 18.4 mm | 600 |

Barcode-Product-Label (BPL)

OSRAM Opto Semiconductors LX XXXX BIN1: XX-XX-X-XXX-X

RoHS Compliant

(6P) BATCH NO: 1234567890 ML Temp ST
X XXX °C X

(1T) LOT NO: 1234567890 (9D) D/C: 1234

Pack: RXX
DEMY XXX
X_X123_1234.1234 X

(X) PROD NO: 123456789(Q)QTY: 9999 (G) GROUP: XX-XX-X-X

The diagram shows a rectangular label with rounded corners. It contains the OSRAM logo and product name at the top left. To the right are fields for 'LX XXXX' and 'BIN1: XX-XX-X-XXX-X'. Below this is 'RoHS Compliant'. The main body of the label is divided into three horizontal sections, each with a barcode and associated text: (6P) BATCH NO: 1234567890, (1T) LOT NO: 1234567890, and (X) PROD NO: 123456789(Q)QTY: 9999. To the right of the lot number is (9D) D/C: 1234. Further right is a 'no moisture' symbol (a circle with a diagonal line and three drops) and 'ML Temp ST X XXX °C X'. Below the lot number is 'Pack: RXX', 'DEMY XXX', and 'X_X123_1234.1234 X'. To the right of the label is a square QR code. A large 'EXAMPLE' watermark is overlaid diagonally across the label.

OHA04563

Dry Packing Process and Materials ⁶⁾



OHA00539

Moisture-sensitive product is packed in a dry bag containing desiccant and a humidity card according JEDEC-STD-033.

Notes

The evaluation of eye safety occurs according to the standard IEC 62471:2006 (photo biological safety of lamps and lamp systems). Within the risk grouping system of this IEC standard, the device specified in this data sheet falls into the class **low risk (exposure time 100 s)**. Under real circumstances (for exposure time, conditions of the eye pupils, observation distance), it is assumed that no endangerment to the eye exists from these devices. As a matter of principle, however, it should be mentioned that intense light sources have a high secondary exposure potential due to their blinding effect. When looking at bright light sources (e.g. headlights), temporary reduction in visual acuity and afterimages can occur, leading to irritation, annoyance, visual impairment, and even accidents, depending on the situation.

Subcomponents of this device contain, in addition to other substances, metal filled materials including silver. Metal filled materials can be affected by environments that contain traces of aggressive substances. Therefore, we recommend that customers minimize device exposure to aggressive substances during storage, production, and use. Devices that showed visible discoloration when tested using the described tests above did show no performance deviations within failure limits during the stated test duration. Respective failure limits are described in the IEC60810.

This device is designed for specific/recommended applications only. Please consult OSRAM Opto Semiconductors Sales Staff in advance for detailed information on other non-recommended applications (e.g. automotive).

Change management for this component is aligned with the requirements of the lighting market.

For further application related information please visit www.osram-os.com/appnotes

Disclaimer

Attention please!

The information describes the type of component and shall not be considered as assured characteristics. Terms of delivery and rights to change design reserved. Due to technical requirements components may contain dangerous substances.

For information on the types in question please contact our Sales Organization.

If printed or downloaded, please find the latest version on the OSRAM OS website.

Packing

Please use the recycling operators known to you. We can also help you – get in touch with your nearest sales office. By agreement we will take packing material back, if it is sorted. You must bear the costs of transport. For packing material that is returned to us unsorted or which we are not obliged to accept, we shall have to invoice you for any costs incurred.

Product and functional safety devices/applications or medical devices/applications

OSRAM OS components are not developed, constructed or tested for the application as safety relevant component or for the application in medical devices.

OSRAM OS products are not qualified at module and system level for such application.

In case buyer – or customer supplied by buyer – considers using OSRAM OS components in product safety devices/applications or medical devices/applications, buyer and/or customer has to inform the local sales partner of OSRAM OS immediately and OSRAM OS and buyer and /or customer will analyze and coordinate the customer-specific request between OSRAM OS and buyer and/or customer.

Glossary

- 1) **Brightness:** Brightness values are measured during a current pulse of typically 10 ms, with a tolerance of +/- 7%.
- 2) **Wavelength:** The wavelength is measured at a current pulse of typically 10 ms, with a tolerance of ± 0.5 nm.
- 3) **Forward Voltage:** The Forward voltage is measured during a current pulse duration of typically 1 ms with a tolerance of $\pm 0.05V$.
- 4) **Typical Values:** Due to the special conditions of the manufacturing processes of semiconductor devices, the typical data or calculated correlations of technical parameters can only reflect statistical figures. These do not necessarily correspond to the actual parameters of each single product, which could differ from the typical data and calculated correlations or the typical characteristic line. If requested, e.g. because of technical improvements, these typ. data will be changed without any further notice.
- 5) **Characteristic curve:** In the range where the line of the graph is broken, you must expect higher differences between single devices within one packing unit.
- 6) **Tolerance of Measure:** Unless otherwise noted in drawing, tolerances are specified with ± 0.1 and dimensions are specified in mm.
- 7) **Tape and Reel:** All dimensions and tolerances are specified acc. IEC 60286-3 and specified in mm.

Revision History

| Version | Date | Change |
|---------|------------|--|
| 1.0 | 2019-01-29 | Initial Version |
| 1.0 | 2019-01-31 | Initial Version |
| 1.1 | 2020-02-18 | Schematic Transportation Box Dimensions of Transportation Box |

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